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LEAKAGE AND PACKAGE-MODE EFFECTS IN MILLIMETER-WAVE IC's

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Session Abstract: If the effects due to leakage or “package modes” are not included in the design of densely packaged microwave or millimeter-wave integrated circuits, particularly at higher frequencies, they can produce unexpected or undesired cross talk, and they can ruin the performance of these circuits. It is therefore essential that we know how to characterize these effects and take them into account. The papers in this session describe both new effects in this category and new techniques to take them into account quantitatively.

**4:00 p.m.–5:30 p.m., Wednesday, June 14, 1989
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